



ALPHA & OMEGA
SEMICONDUCTOR

AON3611

30V Complementary MOSFET

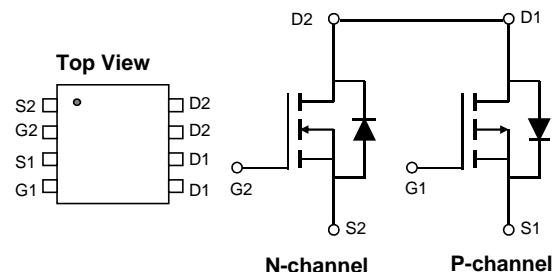
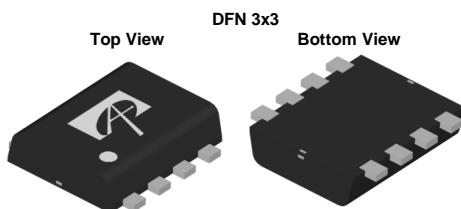
General Description

The AON3611 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs may be used in inverter and other applications.

Product Summary

N-channel	P-channel
V_{DS} (V) = 30V	V_{DS} (V) = -30V
I_D = 5A	I_D = -6A
$R_{DS(ON)} < 50\text{m}\Omega$	$R_{DS(ON)} < 38\text{m}\Omega$
$R_{DS(ON)} < 70\text{m}\Omega$	$R_{DS(ON)} < 62\text{m}\Omega$

($V_{GS} = \pm 10\text{V}$)
($V_{GS} = \pm 10\text{V}$)
($V_{GS} = \pm 4.5\text{V}$)



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Max N-channel	Max P-channel	Units
Drain-Source Voltage	V_{DS}	30	-30	V
Gate-Source Voltage	V_{GS}	± 20	± 20	V
Continuous Drain Current <small>$T_A=25^\circ\text{C}$</small>	I_D	5	-6	A
		3.8	-4.7	
Pulsed Drain Current ^C	I_{DM}	20	-30	W
Power Dissipation ^B <small>$T_A=25^\circ\text{C}$</small>	P_D	2.1	2.5	
		1.3	1.6	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	-55 to 150	°C

Thermal Characteristics: N-channel

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A <small>$t \leq 10\text{s}$</small>	$R_{\theta JA}$	50	60	°C/W
Maximum Junction-to-Ambient ^{A,D} Steady-State		80	98	°C/W
Maximum Junction-to-Lead	$R_{\theta JL}$	48	58	°C/W

Thermal Characteristics: P-channel

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A <small>$t \leq 10\text{s}$</small>	$R_{\theta JA}$	40	50	°C/W
Maximum Junction-to-Ambient ^{A,D} Steady-State		70	85	°C/W
Maximum Junction-to-Lead	$R_{\theta JL}$	38	46	°C/W

N-channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm20\text{V}$			±100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.5	2	2.5	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=10\text{V}, V_{DS}=5\text{V}$	20			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=5\text{A}$ $T_J=125^\circ\text{C}$	40	50		$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=3\text{A}$	64	80		
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}, I_D=5\text{A}$	53	70		$\text{m}\Omega$
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$	0.79	1		V
I_S	Maximum Body-Diode Continuous Current				1.5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=15\text{V}, f=1\text{MHz}$		170		pF
C_{oss}	Output Capacitance		35			pF
C_{rss}	Reverse Transfer Capacitance		23			pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	1.5	2.0	3.0	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, I_D=5\text{A}$		4.05	10	nC
$Q_g(4.5\text{V})$	Total Gate Charge		2	6		nC
Q_{gs}	Gate Source Charge		0.55			nC
Q_{gd}	Gate Drain Charge		1			nC
$t_{\text{D(on)}}$	Turn-On Delay Time	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, R_L=3\Omega, R_{\text{GEN}}=3\Omega$		4.5		ns
t_r	Turn-On Rise Time		1.5			ns
$t_{\text{D(off)}}$	Turn-Off Delay Time		18.5			ns
t_f	Turn-Off Fall Time		15.5			ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=5\text{A}, dI/dt=100\text{A}/\mu\text{s}$	7.5			ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=5\text{A}, dI/dt=100\text{A}/\mu\text{s}$	2.5			nC

A. The value of R_{qJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using $\leq 10\text{s}$ junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{C}$.

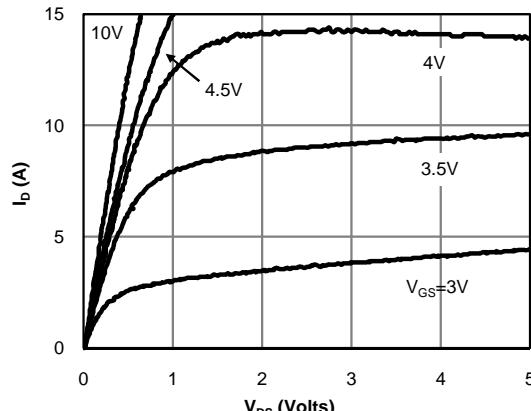
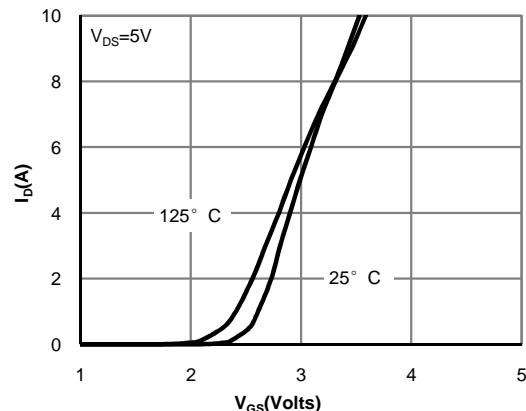
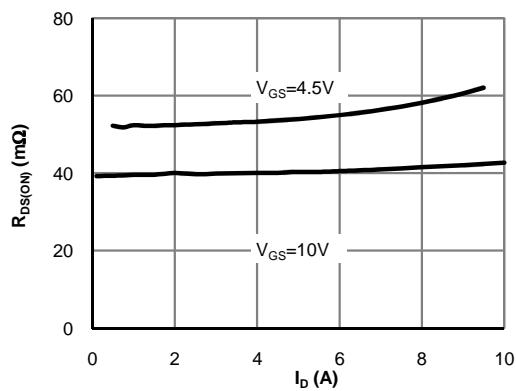
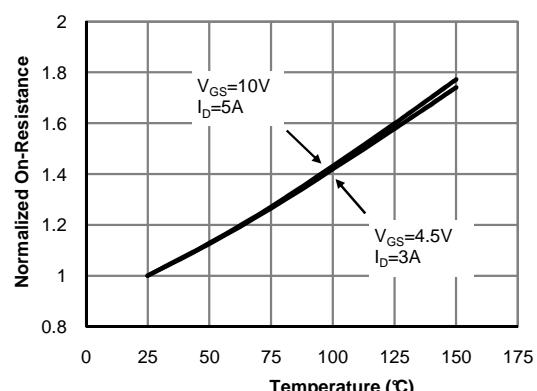
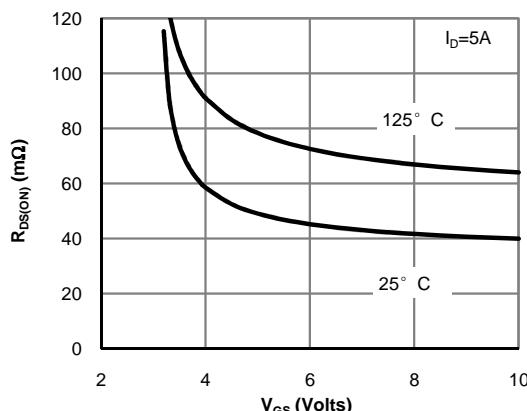
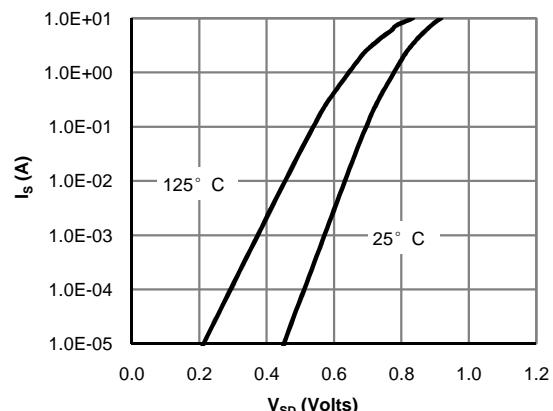
D. The R_{qJA} is the sum of the thermal impedance from junction to lead R_{qJL} and lead to ambient.

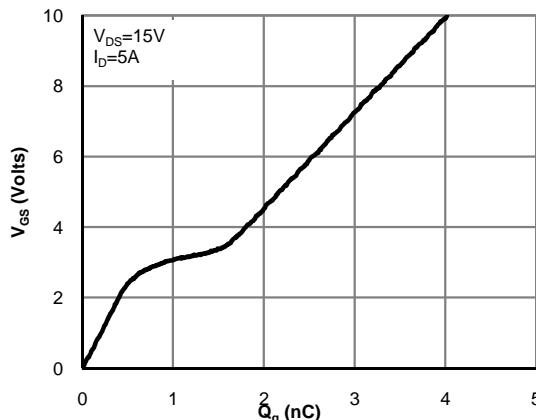
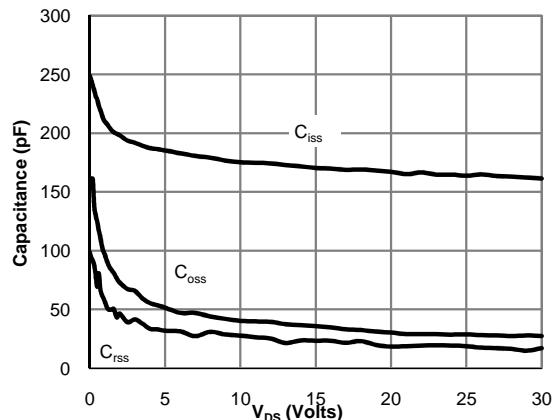
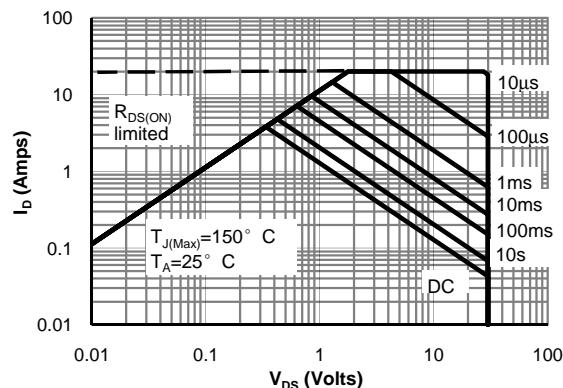
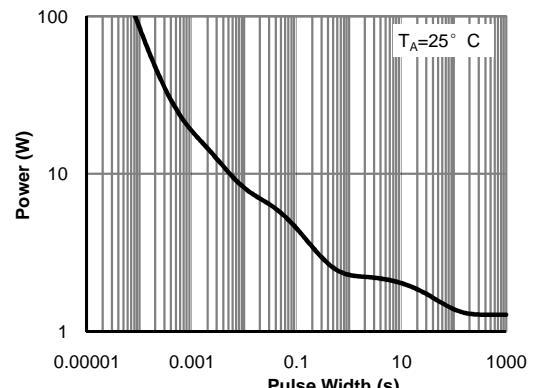
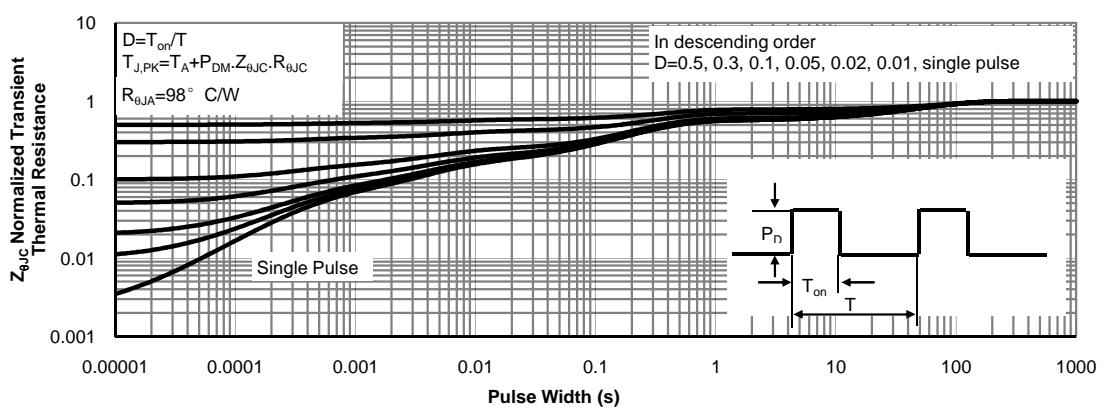
E. The static characteristics in Figures 1 to 6 are obtained using $<300\text{ms}$ pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, assuming a maximum junction temperature of $T_{J(\text{MAX})}=150^\circ\text{C}$. The SOA curve provides a single pulse rating.

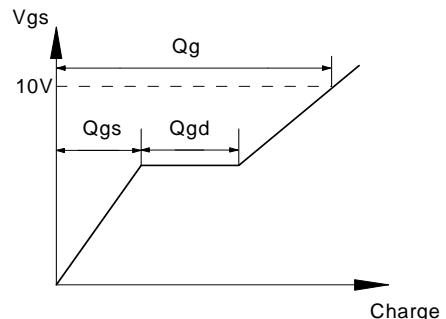
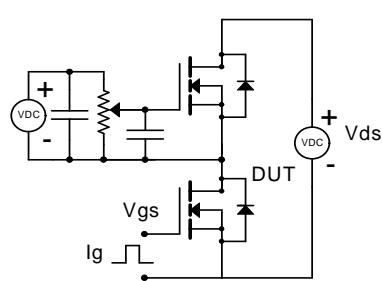
G. The maximum current rating is package limited.

COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS ARE NOT AUTHORIZED. AOS DOES NOT ASSUME ANY LIABILITY ARISING OUT OF SUCH APPLICATIONS OR USES OF ITS PRODUCTS. AOS RESERVES THE RIGHT TO IMPROVE PRODUCT DESIGN, FUNCTIONS AND RELIABILITY WITHOUT NOTICE.

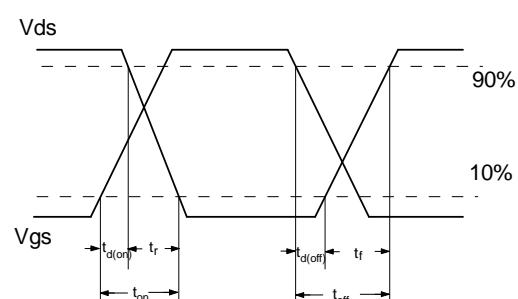
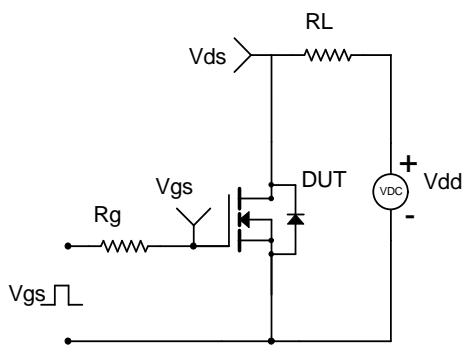
N-channel TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Fig 1: On-Region Characteristics (Note E)

Figure 2: Transfer Characteristics (Note E)

Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

Figure 4: On-Resistance vs. Junction Temperature (Note E)

Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

Figure 6: Body-Diode Characteristics (Note E)

N-channel TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

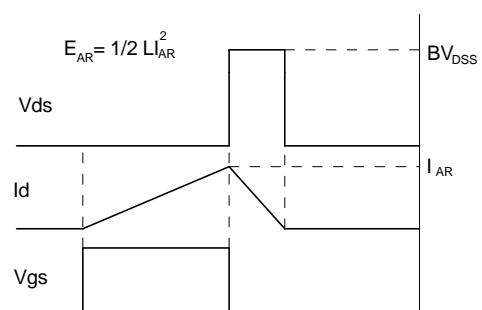
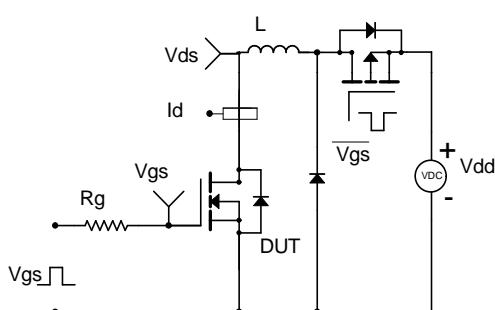
Gate Charge Test Circuit & Waveform



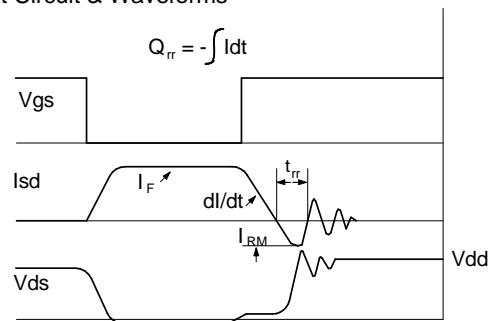
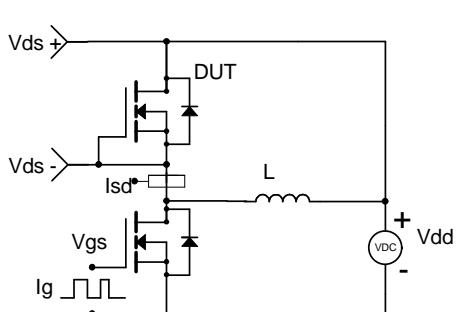
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



P-channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}, V_{GS}=0\text{V}$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-30\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			-1 -5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm20\text{V}$			±100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.4	-1.9	-2.4	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=-10\text{V}, V_{DS}=-5\text{V}$	-30			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}, I_D=-6\text{A}$		30	38	$\text{m}\Omega$
		$T_J=125^\circ\text{C}$ $V_{GS}=-4.5\text{V}, I_D=-4\text{A}$		45	57	
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}, I_D=-6\text{A}$		13		S
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}, V_{GS}=0\text{V}$		-0.76	-1	V
I_S	Maximum Body-Diode Continuous Current				-2	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=-15\text{V}, f=1\text{MHz}$		520		pF
C_{oss}	Output Capacitance			100		pF
C_{rss}	Reverse Transfer Capacitance			65		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		7.5	11.5	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, I_D=-6\text{A}$		9.2	20	nC
$Q_g(4.5\text{V})$	Total Gate Charge			4.6	10	nC
Q_{gs}	Gate Source Charge			1.6		nC
Q_{gd}	Gate Drain Charge			2.2		nC
$t_{\text{D(on)}}$	Turn-On Delay Time	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, R_L=2.5\Omega, R_{\text{GEN}}=3\Omega$		7.5		ns
t_r	Turn-On Rise Time			5.5		ns
$t_{\text{D(off)}}$	Turn-Off Delay Time			19		ns
t_f	Turn-Off Fall Time			7		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-6\text{A}, dI/dt=100\text{A}/\mu\text{s}$		11		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-6\text{A}, dI/dt=100\text{A}/\mu\text{s}$		5.3		nC

A. The value of R_{qJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using $\leq 10\text{s}$ junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{C}$.

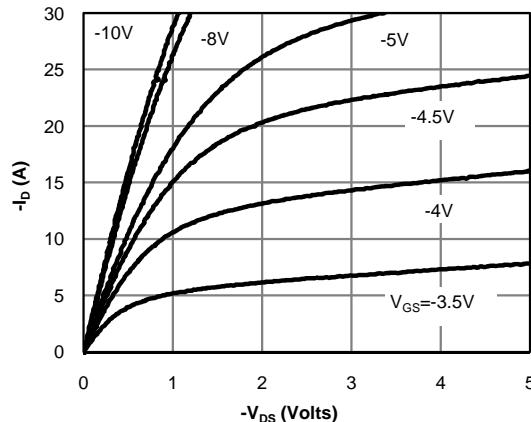
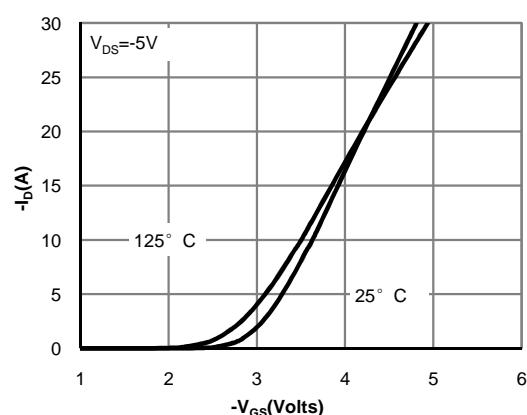
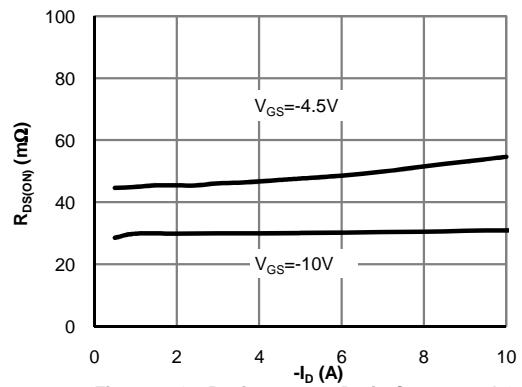
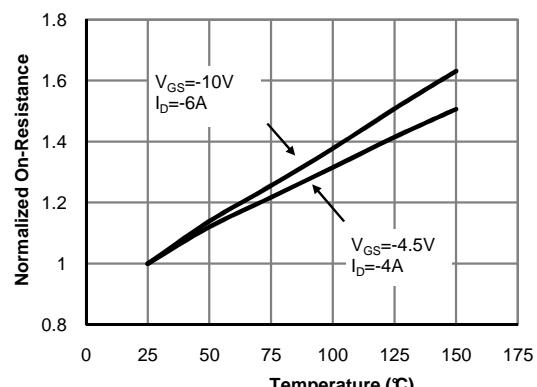
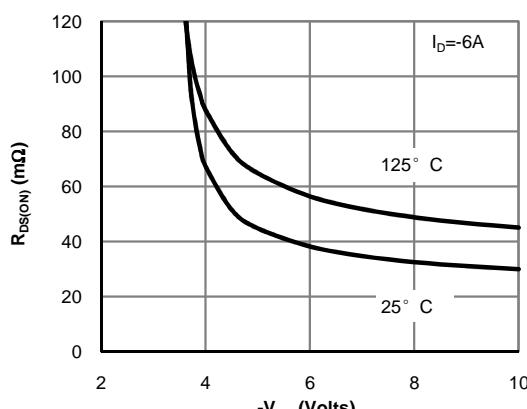
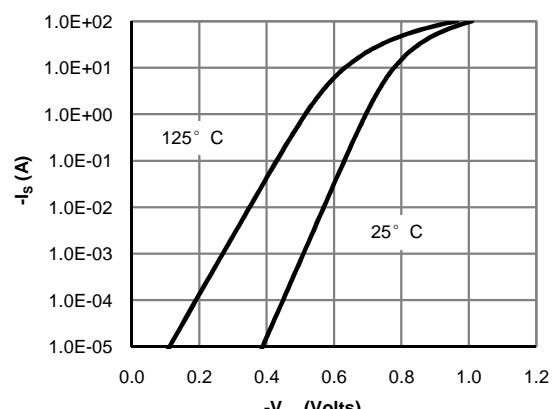
D. The R_{qJA} is the sum of the thermal impedance from junction to lead R_{qJL} and lead to ambient.

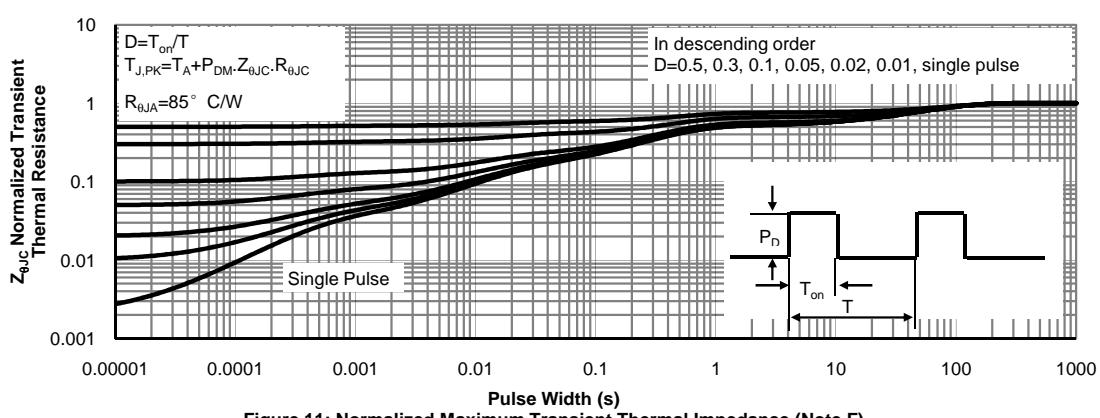
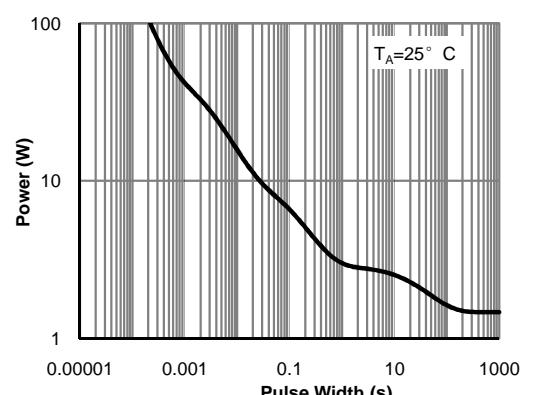
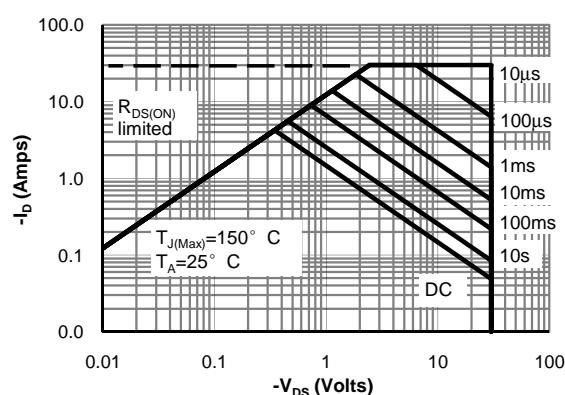
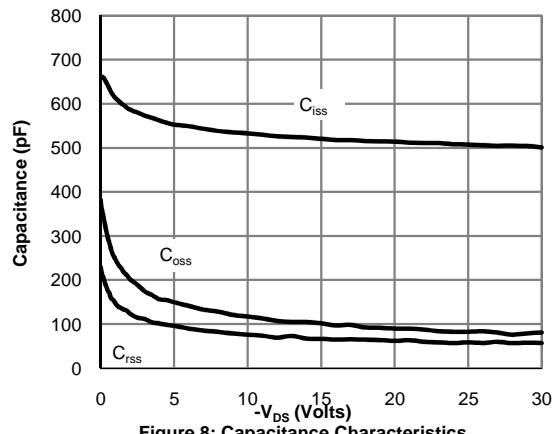
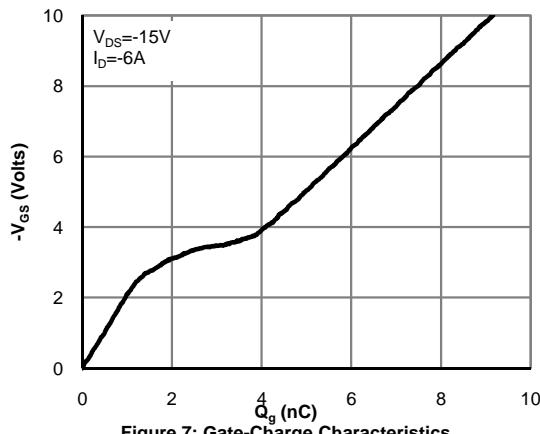
E. The static characteristics in Figures 1 to 6 are obtained using $<300\text{ms}$ pulses, duty cycle 0.5% max.

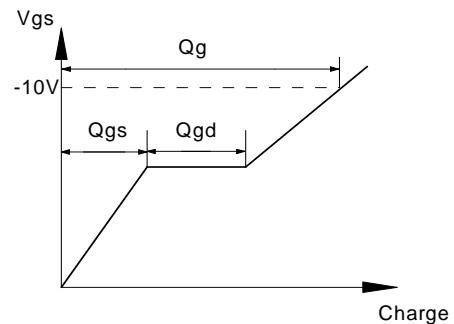
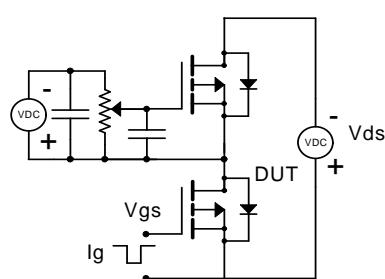
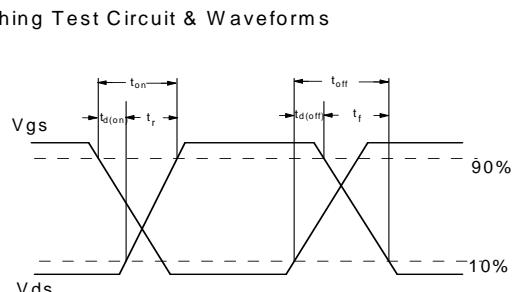
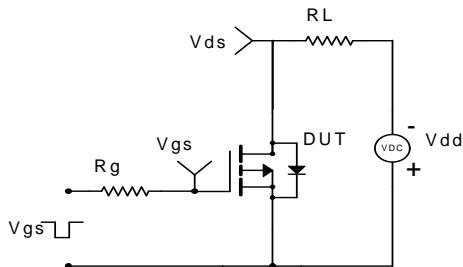
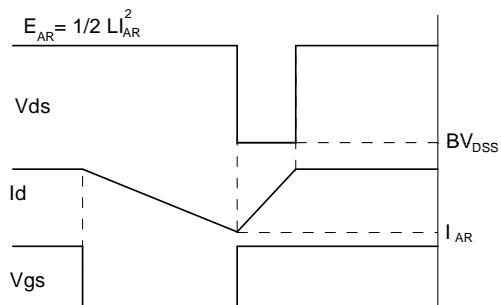
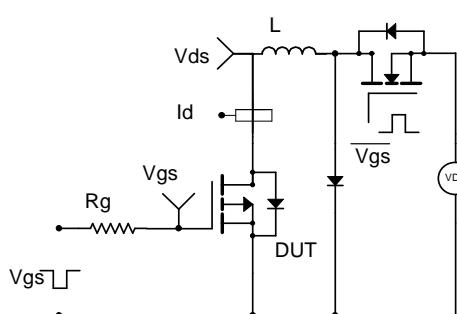
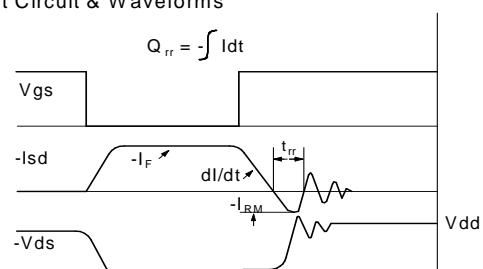
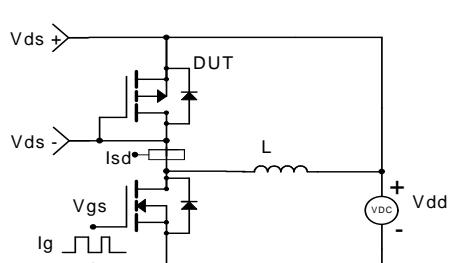
F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, assuming a maximum junction temperature of $T_{J(\text{MAX})}=150^\circ\text{C}$. The SOA curve provides a single pulse rating.

G. The maximum current rating is package limited.

COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS ARE NOT AUTHORIZED. AOS DOES NOT ASSUME ANY LIABILITY ARISING OUT OF SUCH APPLICATIONS OR USES OF ITS PRODUCTS. AOS RESERVES THE RIGHT TO IMPROVE PRODUCT DESIGN, FUNCTIONS AND RELIABILITY WITHOUT NOTICE.

P-channel TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Fig 1: On-Region Characteristics (Note E)

Figure 2: Transfer Characteristics (Note E)

Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

Figure 4: On-Resistance vs. Junction Temperature (Note E)

Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

Figure 6: Body-Diode Characteristics (Note E)

P-channel TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS


Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

Diode Recovery Test Circuit & Waveforms


X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for alpha & omega manufacturer:

Other Similar products are found below :

[AOT1608L](#) [AO4492](#) [AOD478](#) [AOD468](#) [AOZ6135HI](#) [AO5404E](#) [AOD482](#) [AO3402](#) [AOTF10B60D](#) [AOU3N50](#) [AOZ1235QI-01](#)
[AOK42S60L](#) [AON7534](#) [AOD3N50](#) [AO4468](#) [AO3401A](#) [AO3415](#) [AON2403](#) [AOD4130](#) [AOB290L](#) [AOTF42S60L](#) [AOTF190A60L](#)
[AO4404B](#) [AON6756](#) [AO4813](#) [AO3414](#) [aot412](#) [AO4818](#) [AOT270AL](#) [AO6420](#) [AO3442](#) [AOT2918L](#) [AO4616](#) [AO4294](#) [AOZ1020AI](#)
[AON6250](#) [AON6444](#) [AOZ3011PI](#) [AO8820](#) [AOT10N65](#) [AOK20S60L](#) [AOK20N60L](#) [AON6548](#) [AO3415A](#) [AOT470](#) [AOZ8905CI](#)
[AOK60N30L](#) [AOT410L](#) [AON6280](#) [AON6414A](#)